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September 2007

# FDC637BNZ

# N-Channel 2.5V Specified PowerTrench® MOSFET

**20V**, **6.2A**, **24m** $\Omega$ 

## **Features**

- Max  $r_{DS(on)}$  = 24m $\Omega$  at  $V_{GS}$  = 4.5V,  $I_D$  = 6.2A
- Max  $r_{DS(on)} = 32m\Omega$  at  $V_{GS} = 2.5V$ ,  $I_D = 5.2A$
- Fast switching speed
- Low gate charge (8nC typical)
- High performance trench technology for extremely low r<sub>DS(on)</sub>
- SuperSOT™-6 package: small footprint (72% smaller than standard SO-8; low profile (1mm thick)
- HBM ESD protection level > 2kV typical (Note 3)
- Manufactured using green packaging material
- Halide-Free
- RoHS Compliant



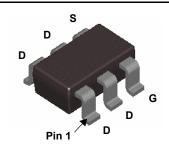
# **General Description**

This N-Channel 2.5V specified MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that has been especially tailored to minimize the on-state resistance and yet maintain low gate charge for superior switching performance.

These devices have been designed to offer exceptional power dissipation in a very small footprint compared with bigger SO-8 and TSSOP-8 packages.

## **Applications**

- DC DC Conversion
- Load switch
- Battery Protection



SuperSOT<sup>TM</sup> -6

# D 1 6 D D 2 5 D G 3 4 S

## MOSFET Maximum Ratings TA= 25°C unless otherwise noted

Symbol	Pa	Ratings	Units		
V <sub>DS</sub>	Drain to Source Voltage			20	V
V <sub>GS</sub>	Gate to Source Voltage			±12	V
	Drain Current -Continuous	T <sub>A</sub> = 25°C	(Note 1a)	6.2	۸
ID	-Pulsed			20	Α
D	Power Dissipation	T <sub>A</sub> = 25°C	(Note 1a)	1.6	14/
$P_{D}$	Power Dissipation	T <sub>A</sub> = 25°C	(Note 1b)	0.8	W
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Tem	-55 to +150	°C		

#### **Thermal Characteristics**

$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	78	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1b)	156	C/VV

## **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
.637Z	FDC637BNZ	SSOT6	7"	8mm	3000 units

# **Electrical Characteristics** $T_J = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	cteristics					
$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	20			V
$\Delta BV_{DSS} \over \Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250μA, referenced to 25°C		10		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 16V, V <sub>GS</sub> = 0V			1	μΑ
$I_{GSS}$	Gate to Source Leakage Current	$V_{GS} = \pm 12V, V_{DS} = 0V$			±10	μΑ

#### On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	0.6	0.8	1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I <sub>D</sub> = 250μA, referenced to 25°C		-3		mV/°C
		$V_{GS} = 4.5V, I_D = 6.2A$		21	24	
r <sub>DS(on)</sub>	r <sub>DS(on)</sub> Static Drain to Source On Resistance	V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 5.2A		26	32	mΩ
	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 6.2A, T <sub>J</sub> = 125°C		30	41		
g <sub>FS</sub>	Forward Transconductance	$V_{DD} = 5V, I_D = 6.2A$		27		S

# **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 0V, f = 1MHz		670	895	pF
C <sub>oss</sub>	Output Capacitance			160	215	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			115	175	pF
$R_g$	Gate Resistance	f = 1MHz		2.1		Ω

# **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time	., ,,,,	8	16	ns
t <sub>r</sub>	Rise Time	$V_{DD} = 10V, I_{D} = 6.2A$ $V_{GS} = 4.5V, R_{GEN} = 6\Omega$	6	12	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	V <sub>GS</sub> = 4.5V, K <sub>GEN</sub> = 002	22	36	ns
t <sub>f</sub>	Fall Time		6	12	ns
Qg	Total Gate Charge	1, 15)()( 10)(	8	12	nC
Q <sub>gs</sub>	Gate to Source Gate Charge	$V_{GS} = 4.5V, V_{DD} = 10V,$ $I_{D} = 6.2A$	1.3		nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge	1D - 0.2A	2.2		nC

#### **Drain-Source Diode Characteristics**

Is	Maximum Continuous Drain-Source Diode Forward Current			1.3	Α	
$V_{SD}$	Source to Drain Diode Forward Voltage $V_{GS} = 0V$ , $I_S = 1.3A$ (Note 2)		0.7	1.2	V	
t <sub>rr</sub>	Reverse Recovery Time	I <sub>E</sub> = 6.2A. di/dt = 100A/μs		15	27	ns
Q <sub>rr</sub>	Reverse Recovery Charge	1F = 6.2A, α/αι = 100A/μS		5	10	nC

<sup>1.</sup>  $R_{\theta JA}$  is determined with the device mounted on a  $1\text{in}^2$  pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta JA}$  is determined by the user's board design.



a. 78°C/W when mounted on a 1 in<sup>2</sup> pad of 2 oz copper.



b. 156°C/W when mounted on a minimum pad of 2 oz copper.

<sup>2.</sup> Pulse Test: Pulse Width <  $300\mu\text{s},$  Duty cycle < 2.0%.

<sup>3.</sup> The diode connected between the gate and source serves only as protection against ESD. No gate overvoltage rating is implied.

## Typical Characteristics T<sub>.I</sub> = 25°C unless otherwise noted

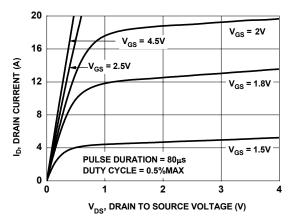


Figure 1. On-Region Characteristics

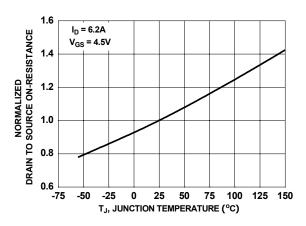


Figure 3. Normalized On-Resistance vs Junction Temperature

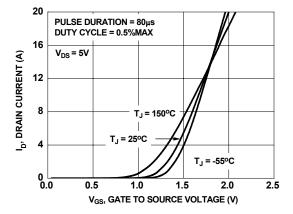


Figure 5. Transfer Characteristics

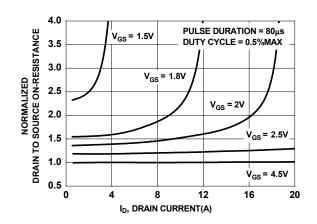


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

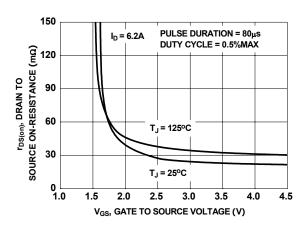


Figure 4. On-Resistance vs Gate to Source Voltage

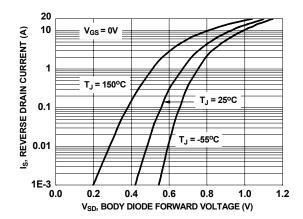


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

# Typical Characteristics T<sub>J</sub> = 25°C unless otherwise noted

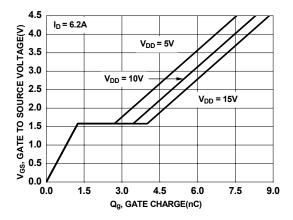
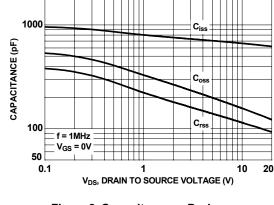


Figure 7. Gate Charge Characteristics



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Figure 8. Capacitance vs Drain to Source Voltage

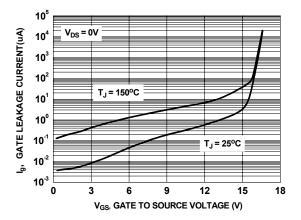


Figure 9. Gate Leakage Current vs Gate to Source Voltage

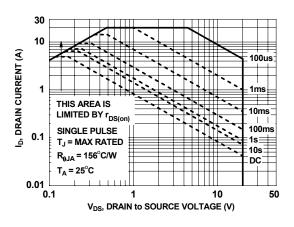


Figure 10. Forward Bias Safe Operating Area

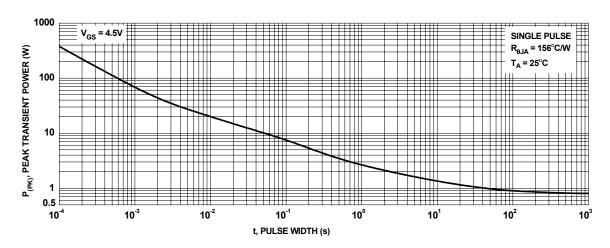


Figure 11. Single Pulse Maximum Power Dissipation

# Typical Characteristics T<sub>J</sub> = 25°C unless otherwise noted

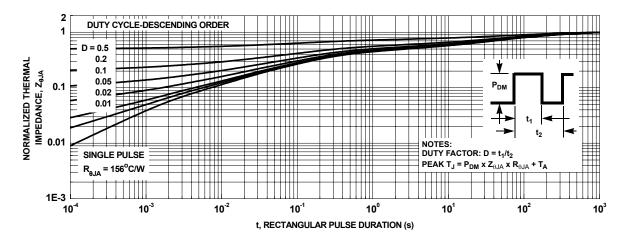


Figure 12. Transient Thermal Response Curve



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